

IN THE CLAIMS:

Please AMEND claims 1, 2 and 8-10, as follows. Note that all the claims currently pending in this application, including those not currently being amended, have been reproduced below for the Examiner's convenience.

1. (Currently Amended) A projection exposure apparatus, comprising:
 - a continuous emission excimer laser, having a resonator, for providing laser light;
 - an illumination optical system for ~~illuminating a pattern of a reticle with~~ receiving the laser light from the continuous emission excimer laser and for illuminating a pattern of a reticle with the laser light;
 - a projection optical system, comprising a lens system made of a substantially single glass material, for projecting the illuminated pattern of the reticle onto a ~~substrate, wherein~~ material substrate; ~~said projection optical system is provided by a lens system made of a substantially single glass~~
 - an injection laser for injecting light into a the resonator of said continuous emission excimer laser, wherein a design wavelength of the injection laser is equal to a design wavelength of the continuous emission excimer laser;
 - a wavemeter for measuring the wavelength of the laser light from said continuous emission excimer laser and for producing a signal; and
 - changing means for changing a resonator length of said continuous emission excimer laser on the basis of a the signal from said wavemeter so that the wavelength of the laser

light from said continuous emission excimer laser becomes equal to the design wavelength of the continuous emission excimer laser.

2. (Currently Amended) An apparatus according to Claim 1, wherein said injection laser comprises a pulse emission excimer laser including a resonator having a band narrowing element, said apparatus further comprises (i) a wavemeter for measuring the wavelength of light from said pulse emission excimer ~~laser~~, laser and for producing a signal and (ii) an actuator, wherein said actuator actuates the a band narrowing element in a the resonator of said pulse emission excimer laser ~~is actuated~~ on the basis of a the signal from said wavemeter so that the wavelength of said pulse emission excimer laser becomes equal to the predetermined wavelength.

3. (Cancelled)

4. (Previously Presented) An apparatus according to Claim 1, wherein said changing means includes at least one of shifting means for shifting a mirror in said resonator and pressure changing means for changing a pressure of an excitation gas.

5. (Previously Presented) An apparatus according to Claim 1, wherein the reticle is illuminated with slit-like light having one of a rectangular shape and an arcuate shape, and wherein said apparatus further comprises scanning means for scanningly moving the reticle and

the substrate relative to the slit-like light and to said projection optical system such that the substrate is exposed to the pattern of the reticle.

6. (Original) An apparatus according to Claim 1, wherein the half bandwidth of the wavelength spectrum of the laser light is not greater than 0.1 pm, and an image of a linewidth of 0.13 micron can be produced.

7. (Original) An apparatus according to Claim 1, wherein the half bandwidth of the wavelength spectrum of the laser light is not greater than 0.08 pm, and an image of a linewidth of 0.09 micron can be produced.

8. (Currently Amended) An apparatus according to Claim 1, wherein said excimer laser is an ArF excimer laser, and ~~wherein~~ the glass material is SiO₂.

9. (Currently Amended) An apparatus according to Claim 1, wherein said excimer laser is an F₂ excimer laser, and ~~wherein~~ the glass material is one of CaF₂, BaF₂ and MgF₂.

10. (Currently Amended) An apparatus according to Claim 1, wherein said lens system includes lens elements of a number not less than ten, and ~~wherein~~ a first one or first two lens elements of the lens system in an order from the substrate side are made of one of CaF₂, BaF₂ and MgF₂.

11. (Original) A device manufacturing method comprising the steps of:

 exposing a substrate to a device pattern by use of a projection exposure apparatus

as recited in Claim 1; and

 developing the exposed substrate.